

SPECIFICATION FOR LCD MODULE

MODULE NO: AFK1024600A0-7.0INTM **REVISION NO: V01**

Customer's Approval:					
	SIGNATURE	DATE			
	SIGNATORE	DAIL			
PREPARED BY (RD ENGINEER)					
CHECKED BY					
APPROVED BY					

Records of Revision

DATE	REF.PAGE PARAGRAPH DRAWING No.	REVISED No.	SUMMARY	REMARK
2019-08-21		V01	First Issue	

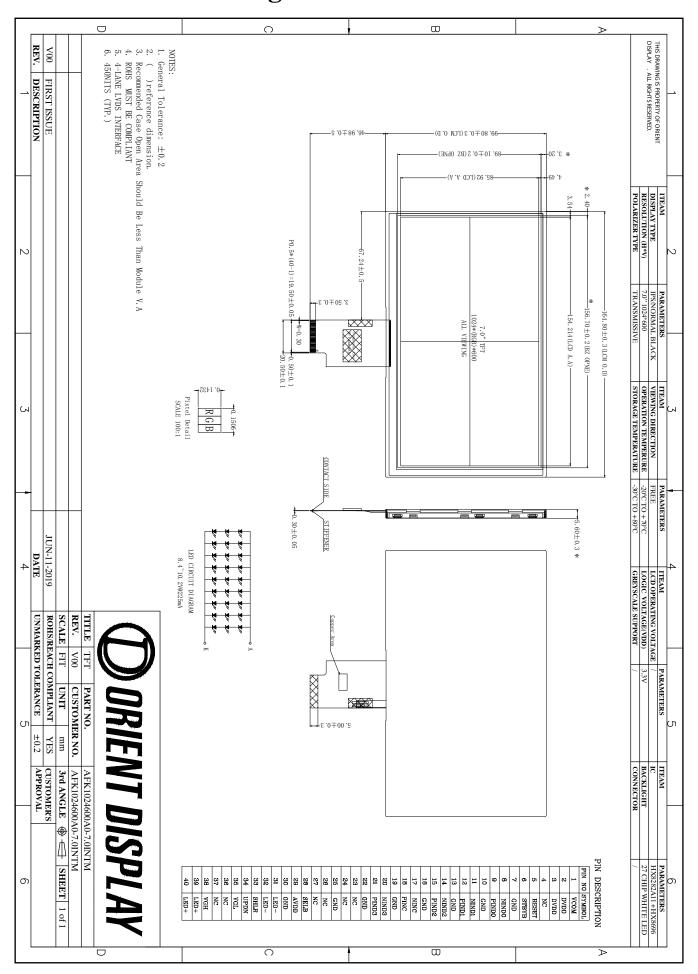
Contents

1. General Specification.	4
2. Mechanical Drawing	5
3. Block Diagram	6
4. Interface Pin Function	7
5. Absolute Maximum Ratings	9
6. Electrical Characteristics	10
7. Optical Characteristics	11
8. Timing Characteristics	14
9. Standard Specification for Reliability	16
10. Specification of Quality Assurance	18
11. Handling Precaution	27
12. Packing Method	28

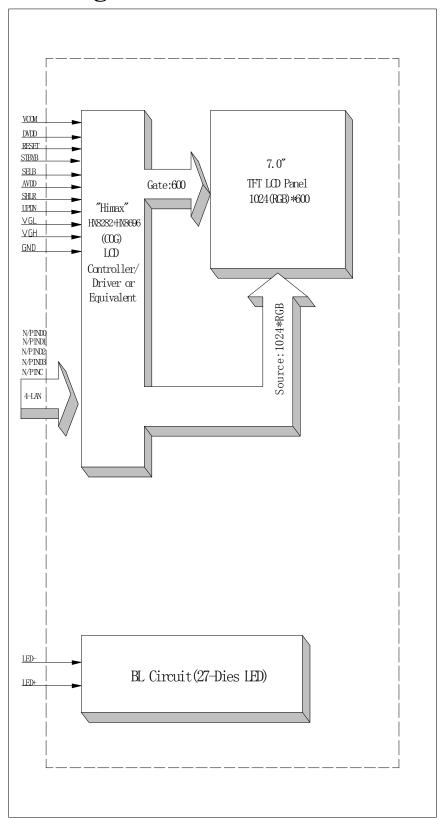
1. General Specification

Item	Contents	Unit
LCD type	TFT/Transmissive	
Module size (W*H*T)	164.80*99.80*5.60	mm
Active size (W*H)	154.21*85.92	mm
Pixel pitch (W*H)	0.1506*0.1432	mm
Number of dots	1024*600	
Driver IC	HX8282-A11+HX8696-A00	
Interface type	4-lan LVDS	
Top polarizer type	Anti-Glare	
Recommend viewing direction	All	O'clock
Gary scale inversion direction	-	O'clock
Colors	27-Dies white LED	
Backlight type	Without	

2. Mechanical Drawing

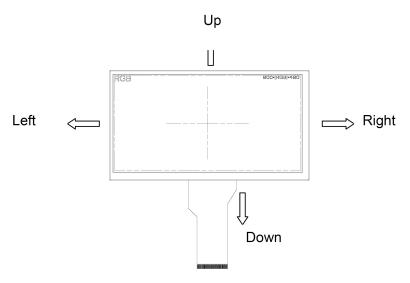


3. Block Diagram



4. Interface Pin Function

Pin No.	Symbol	Description			
1	VCOM	Common voltage			
2	DVDD	Power Voltage for digital circuit			
3	DVDD	Power Voltage for digital circuit			
4	NC	No connection			
5	RESET	Global Reset Pin			
6	STBYB	Standby mode, Normally pulled high STBYB = "1", normal operation STBYB= "0", timing controller, source driver will turn off, all output are High-Z			
7	GND	Power ground			
8	NIND0	- LVDS differential data input			
9	PIND0	+ LVDS differential data input			
10	GND	Power ground			
11	NIND1	- LVDS differential data input			
12	PIND1	+ LVDS differential data input			
13	GND	Power ground			
14	NIND2	- LVDS differential data input			
15	PIND2	+ LVDS differential data input			
16	GND	Power ground			
17	NINC	-LVDS differential CLOCK input			
18	PINC	+ LVDS differential CLOCK input			
19	GND	Power ground			
20	NIND3	- LVDS differential data input			
21	PIND3	+ LVDS differential data input			
22	GND	Power ground			
23	NC	No connection			
24	NC	No connection			
25	GND	Power ground			
26	NC	No connection			
27	NC	No connection			
28	SELB	6bit/8bit mode select			
29	AVDD	Power for Analog Circuit			
30	GND	Power ground			
31	LED-	Cathode of LED backlight			
32	LED-	Cathode of LED backlight			
33	SHLR	Horizontal inversion			
34	UPDN	Vertical inversion			
35	VGL	Gate OFF Voltage			
36	NC	No connection			
37	NC	No connection			
38	VGH	Gate ON Voltage			
39	LED+	Anode of LED backlight			
40	LED+	Anode of LED backlight			



Note1: If LVDS input data is 6 bits ,SELB must be set to High; If LVDS input data is 8 bits ,SELB must be set to Low.

Note2: When SHLR="0", set right to left scan direction. When SHLR="1", set left to right scan direction.

When UPDN="0", set top to bottom scan direction. When UPDN="1", set bottom to top scan direction.

5. Absolute Maximum Ratings

Parameter	Symbol	Min	Max	Unit
Supply Voltage For Logic	DVDD	-0.3	3.96	V
Supply Voltage For Analog	AVDD	-0.5	14.85	V
Power supply	VGH	-0.3	40	V
Power supply	VGL	-20	0.3	V
Power supply	VGH - VGL	-	40	V
Supply current (One LED)	I_{LED}		30	mA
Operating temperature	Тор	-20	+70	С
Storage temperature	T_{ST}	-30	+80	С

Note: The absolute maximum rating values of this product are not allowed to be exceeded at any times. Should a module be used with any of the absolute maximum ratings exceeded, the characteristics of the module may not be recovered, or in an extreme case, the module may be permanently destroyed.

6. Electrical Characteristics

6.1 Input Power

Item	Symbol	Min	Тур.	Max	Unit	Applicable terminal
Supply Voltage For Logic	DVDD	2.3	3.3	3.6	V	
Supply Voltage For Analog	AVDD	8.9	9	9.1	V	
Power supply	VGH	17	18	19	V	
Power supply	VGL	-6.5	-6.0	-5.5	V	
Power supply	VCOM	3.0	3.15	3.3	V	
Input Voltage	$V_{\rm IL}$ $V_{\rm IH}$	0 0.7 DVDD	-	0.3DVDD DVDD	V	
Input leakage Current	I_{LKG}	-		-	μА	

6.2 Backlight Driving Conditions

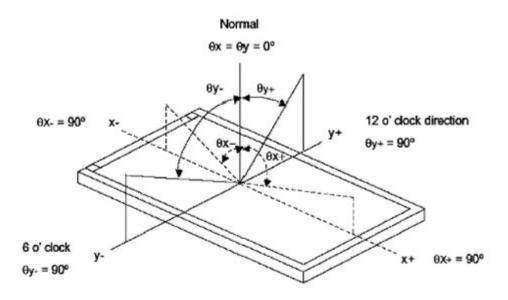
Itom	Symbol		Value		Unit	Remar	
Item	Symbol	Min.	Тур.	Max.	Unit	k	
Voltage for LED Backlight	V _F	8.7	9.6	9.9	V	I _L =225mA	
Current for LED Backlight	IL		225		mA		
Power Consumption	P		1.728		W		
LED Life Time		30,000	50,000		Hr	Note	

Note: Brightness to be decreased to 50% of the initial value at ambient temperature TA=25°C

7. Optical Characteristics

Idele	ITEM		CONDITIONS	SPEC	IFICA	ΓΙΟΝS	UNIT	NOTE
ITEM		SYMBOL	CONDITIONS	MIN	TYP.	MAX		
Lumina	nce	L	IL =225mA	360	450	630	Cd/m ²	
Contrast	Ratio	CR	θ=0°	600	800			
Dagnanga	Times	Ton	25℃		13	20		
Response	Time	Toff	25℃		15	25	ms	
	Red	XR						
	Red	YR						
	Green	XG	Viewing normal angle					
CIE Color	Giccii	YG						
Coordinate	Blue	Хв						
	Diuc	YB						
	White	Xw		0.279	0.319	0.359		
	WIIIC	Yw		0.312	0.352	0.392		
	Hor.	$ heta_{\scriptscriptstyle X+}$		80	85			
Viewing Angle	1101.	$\theta_{\scriptscriptstyle X-}$	CR≥10	80	85		- Degree	Gray scale
	Ver.	$ heta_{\scriptscriptstyle Y+}$	CIC_10	80	85		Degree	inversion
	V C1.	$ heta_{\scriptscriptstyle Y-}$		80	85			
Uniformity	Un			80			%	

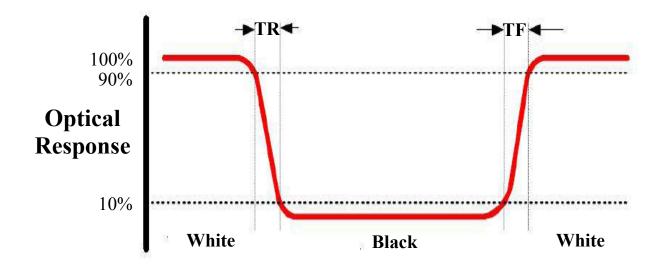
Note 1: Definition of Viewing Angle θx and θy :



Note 2: Definition of contrast ratio CR:

$$CR = \frac{Luminance\ of\ white\ state}{Luminance\ of\ black\ state}$$

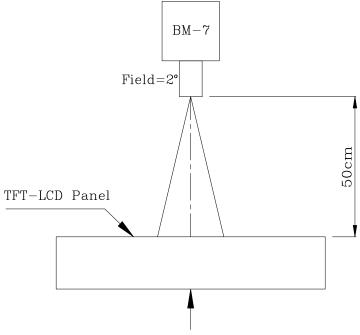
Note 3: Definition of Response Time(Tr,Tf)



Note 4: Definition of Luminance

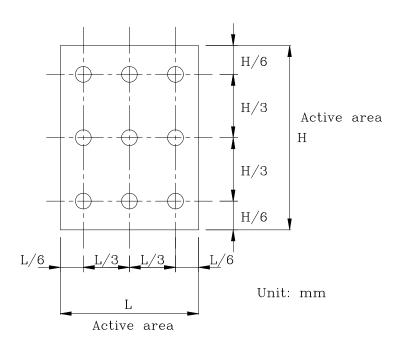
①The Brightness Test Equipment Setup

Field=2°(As measuring "black" image, field=2°is the best testing condition)



The center of the screen

2 The Brightness Test Point Setup



8. Timing Characteristics

8.1 LVDS Timing Diagram

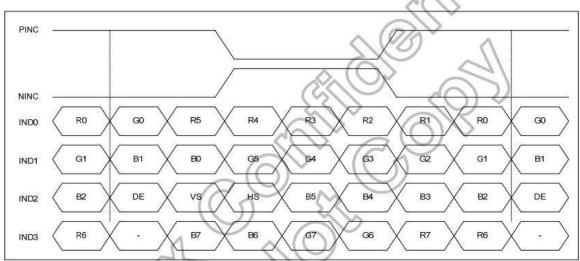


Figure 10.5: 8-bit LVDS Input

Parameter	Symbol		Spec.			Condition	
Faranielei	Symbol	Min. Typ.		Max.	Unit	Condition	
Clock frequency	RXFCLK	20	11-10	71	MHz	-1	
Input data skew margin	T _{RSKM}	500	B		pS	$ V_{ID} $ =400mV R _{XVCM} =1.2V R _{XFCLK} =71MHz	
Clock high time	TLVCH	(2)	4/(7* R _{XFCLK})	(=)	ns		
Clock low time	T _{LVCL}	(\mathbf{Q})	3/(7* R _{XFCLK})	(m)	ns	. : ≡ :	
PLL wake-up time	TemPLL		-	150	μs	(#)	

Table 10.2: LVDS mode AC electrical characteristics

8.2 Power on/off

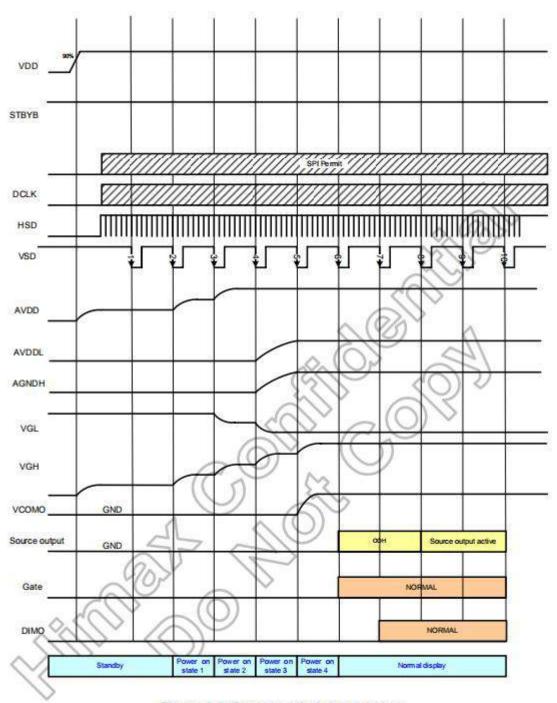


Figure 8.1: Power on timing sequence

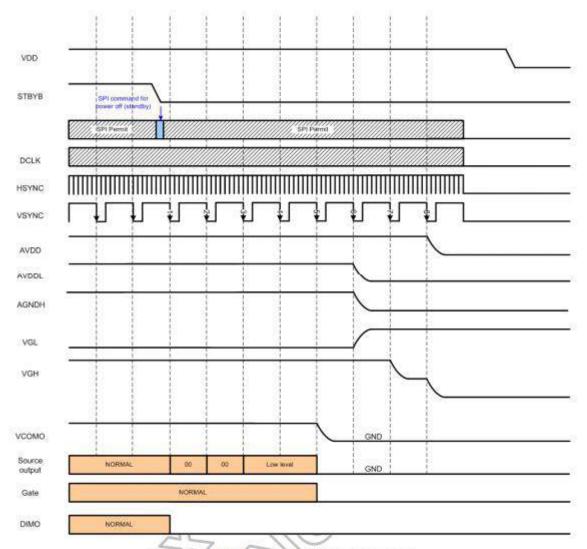


Figure 8.2: Power off timing sequence

Note: Low level=3FH, when NBW=L (Normally white) Low level=00H, when NBW=H (Normally black)

9. Standard Specification for Reliability

9.1Standard Specification for Reliability of LCD Module

No	Test Item	Condition	Remarks
1	High Temperature Operation	Ts = $+70$ °C, 240 hours	IEC60068-21:2007 GB2423.2-2008
2	Low Temperature Operation	Ta = -20°C, 240 hours	IEC60068-2-1:2007 GB/2423.1-2008
3	High Temperature Storage	$Ta = +80^{\circ}C$, 240 hours	IEC60068-21:2007 GB/2423.2-2008
4	Low Temperature Storage	$Ta = -30^{\circ}C$, 240 hours	IEC60068-21:2007 GB/2423.1-2008
5	Storage at High Temperature and Humidity	Ta = $+60^{\circ}$ C, 90% RH max,240hours	IEC60068-2-78 :2001 GB/T2423.3—2006
6	Thermal Shock (non- operation)	-30°C 30 min~+80°C 30 min, Change time:5min, 20 Cycle	Start with cold temperature, End with high temperature, IEC60068-214:1984, GB/2423.22-2002
7	ESD	C=150pF,R=330Ω,5point/panel Air:±8Kv,5times; Contact:±4Kv,5times (Environment:15°C~35°C, 30%~60%.86Kpa~106Kpa)	IEC61000-42:2001 GB/T17626.2-2006
8	Vibration Test	Frequency range:10~55Hz Stroke:1.5mm Sweep:10Hz~55Hz~10Hz 2 hours for each direction of X.Y.Z (6 hours for total)	IEC60068-2-6:1982 GB/T2423.101995
9	Mechanical Shock (Non Op)	Half Sine Wave60G 6ms, ±X,±Y,±Z 3times for each direction	IEC60068-2-27:1987 GB/T2423.5—1995
10	Package Drop Test	Height:80cm, 1corner,3 edges,6 surfaces	IEC60068-2-32:1990 GB/T2423.8—1995

Note1: Ts is the temperature of panel's surface. Note2: Ta is the ambient temperature of sample.

9.2 Testing Conditions and Inspection Criteria

For the final test, the testing sample must be stored at room temperature for 24 hours. After the tests listed in Table 9.2, standard specifications for reliability will be executed in order to ensure stability.

No.	Item	Test Model	In section Criteria
01	Current Consumption	Refer To Specification	The current consumption should conform to the product specification.
02	Contrast	Refer To Specification	After the tests have been executed, the contrast must be larger than half of its initial value prior to the tests.
03	Appearance	Visual inspection	Defect free.

9.3 MTBF

MTBF	Functions, performance, appearance, etc. shall be free from remarkable deterioration within 50,000 hours under ordinary operating and storage conditions room temperature ($25\pm5^{\circ}$ C), normal humidity ($50\pm10\%$ RH), and in area not exposed to direct sun light.
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10. Specification of Quality Assurance

This standard of Quality Assurance confirms to the quality of LCD module products supplied by ODNA.

10.1 Quality Test

Before delivering, the supplier should conduct the following tests to confirm the quality of products.

- Electrical-Optical Characteristics: According to the individual specification to test the product.
- Appearance Characteristics: According to the individual specification to test the product.
- Reliability Characteristics: According to the definition of reliability on the specification for testing products.

10.2 Delivery Test

Before delivering, the supplier should conduct the delivery test.

- Test method: According to MIL-STD105E.General Inspection Level II take a single Time.
- The defects classify of AQL as following:

Major defect: AQL = 0.65 Minor defect: AQL = 1.5 Total defects: AQL = 1.5

10.3 Non-conforming Analysis & Deal With Manners

10.3.1 Non-conforming Analysis

- Purchaser should provide the data detail of non-conforming sample and the non-conforming.
- After receiving the data detail from purchaser, the analysis of non-conforming should be finished within two weeks.
- If the analysis can't be finished on time, supplier must notice purchaser 3 days in advance.

10.3.2 Disposition of non-conforming

- If any product defect be found during assembling, supplier must change the good for every defect after confirmation.
- Both supplier and customer should analyze the reason and discuss the disposition of non-conforming when the reason of nonconforming is not sure.

10.4 Agreement items

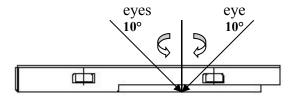
Both parties should negotiate together when the following problems happen.

- There is any problem of standard of quality assurance, and both sides should agree that it must be modified.
- There is any argument item which does not record in the standard of quality assurance.
- Any other special problem.

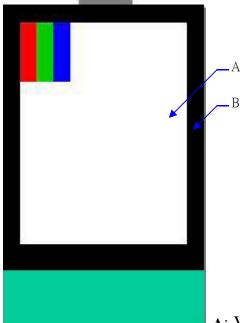
10.5 Standard of The Product Appearance Test

10.5.1 Manner of appearance test

- The test must be under 20W × 2 or 40W fluorescent light, and the distance of view must be at 30±5cm.
- When test the model of transmissive product must add the reflective plate.
- The test direction is base on around 10° of vertical line.
- Temperature: 25±5°C Humidity: 60±10%RH



• Definition of area:



A: Viewing area B: Outside viewing area

10.5.2 Basic principle

- When the standard can not be described, AQL will be applied.
- The sample of the lowest acceptable quality level must be negotiated by both supplier and customer when any dispute happened.

• New item must be added on time when it is necessary.

10.6 Inspection Specification

NO.	Item	Criterion				AQL
01	Electrical Testing	 1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character, dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 LCD viewing angle defect. 1.7 Mixed product types. 1.8 Flicker 			0.65	
02	Black or White spots or Bright spots or Color spots on LCD (Display only)	 2.1 White and black or color spots on display ≤ 0.25mm, no more than Five spots. 2.2 Densely spaced: No more than three spots within 3mm. 			1.5	
LCD and Touch Panel black spots, white spots, contaminati on (non – display)	3.1 Round type: As follo $\Phi = (X+Y)/2$ * Densely spaced: No		Size(mm) $\Phi \le 0.10$ $0.10 < \Phi \le 0.20$ $0.20 < \Phi \le 0.25$ $0.25 < \Phi \le 0.30$ $0.30 < \Phi$	Acceptable Q'ty Accept no dense 1 1 0 0 0 vo spots within 3mm.	1.5	
	spots, contaminati on (non –	3.2 Line type: (As follows * Dens	Length(mm) L<2.5	mg) Width(mm) $W \le 0.02$ $W < 0.08$ $0.08 \le W$	Acceptable Q'ty Accept no dense 1 Rejection wo lines within 3mm.	1.5

Item	Criterion			AQL
	If bubbles are visible,	Size Φ(mm)	Acceptable Q'ty	
Polarizer	judge using black spot specifications, not easy	$\Phi \leq 0.30$	Accept no dense	
bubbles	to find, must check in	$0.30 < \Phi \le 0.50$	0	1.5
	specify direction	0.50< Φ ≤ 1.00	0	
		1.00< Ф	0	
		Total Q'ty	0	
Scratches	Follow NO.3 -2 Line Type.			
Chipped glass	k: Seal width t: Glass thickness L: Electrode pad length 6.1 General glass chip: 6.1.1 Chip on panel surface and crack $z = 1/2t$ Not over via area $z = 1/2t < z \le 2t$ Not exceed $z = 1/2t$ Unit: mm $z = 1/2t$ If there are 2 or more chips, x is 6.1.2 Corner crack: $z = 1/2t$ Not over via area $z = 1/2t$ Not over via area $z = 1/2t$ Not over via area	a: LCD side length kk between panels: $x: Chip lengton in the control of each in the con$	chip	1.5
	Polarizer bubbles Scratches Chipped	Polarizer bubbles Follow NO.3 -2 Line Type. Symbols: x: Chip length y: Chip width t: Glass thickness L: Electrode pad length 6.1 General glass chip: 6.1.1 Chip on panel surface and crace Chipped glass	Polarizer bubbles If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction Scratches Follow NO.3 -2 Line Type. Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length 6.1 General glass chip: 6.1.1 Chip on panel surface and crack between panels: $ z: Chip thickness y: Chip width x \times Chip length x \times 2MM \$	Polarizer bubbles If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction Scratches Follow NO.3 -2 Line Type. Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length 6.1 General glass chip: 6.1.1 Chip on panel surface and crack between panels:

NO.	Item	Criterion	AQL		
		Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length 7.2 Protrusion over terminal: 7.2.1 Chip on electrode pad:			
		y: Chip width x: Chip length z: Chip thickness			
		$y \le 0.5 \text{mm} \qquad x \le 2 \text{MM} \qquad 0 < z \le t$			
07	Glass crack	7.2.2 Non-conductive portion:			
		y: Chip width x: Chip length z: Chip thickness			
		$y \le L \qquad x \le 2MM \qquad 0 < z \le t$			
		 If there chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. If the product will be heat sealed by the customer, the alignment mark must mot be damaged. 7.2.3 Substrate protuberance and internal crack y: width x: length			
		y. width X . length $y \le 1/3L$ $X \le 2MM$			

NO.	Item	Criterion	AQL
08	Cracked glass	No crack is allowed.	
09	Backlight elements	 9.1 Illumination source flickers when lit. 9.2 Spots or scratches that appear when lit must be judged. Using LCD spot, lines and contamination standards. 9.3 Backlight doesn't light or color is wrong. 	
10	Bezel	No scratches with W>0.1 and Length>2.5mm.	
11	PCB、COB	 11.1 COB seal may not have pinholes larger than 0.2mm or contamination. 11.2 COB seal surface may not have pinholes through to the IC. 11.3 The height of the COB should not exceed the height indicated in the assembly diagram. 11.4 There may not be more than 2mm of sealant outside the seal area on PCB. And there should be no more than three places. 11.5 Parts on PCB must be the same as on the production characteristic chart, There should be no wrong parts, missing parts or excess parts. 11.6 The jumper on the PCB should conform to the product characteristic chart. 	
12	FPC	FPC damage per IPC guidelines.(IPC-A-610) Nicks or damage along the edges of the flexible printed cir-cuitry and cutouts,providing the penetration does not exceed 50% of the distance from the edge to the nearest conductor to 2.5mm[0.1in], Whichever is less.	1.5
13	Soldering	 13.1 No cold solder joints, missing solder connections, oxidation or icicle. 13.2 No short circuits in components on PCB or FPC. 13.3 Soldering per IPC guidelines.(IPC-A-610) 	1.5 0.65

NO.	Item	Criterion			
14	Touch Panel Chipped glass	k: Seal width t: 'L: Electrode pad len 14.1 General glass con 14.1.1 Chip on pane zero z: Chip thickness Z≦t O Unit: mm	hip: I surface and crack between the surface and crack between th	x: Chip length x≤2MM	
		z: Chip thickness	y: Chip width	x: Chip length	
		z≦t	≤ 1/2 k and not over viewing area	x≦2MM	
		○ Unit: mm○ If there are 2 or n	nore chips, x is the total	length of each chip	

NO.	Item	Criterion	AQL	
15	Touch Panel(Fish eye dent and bubble on film)	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	1.5	
16	Touch Panel Newton ring	Newton ring dimension $\leq 1/2$ touch panel area and not affect font and line distortion($\leq 2.5\%$), it is acceptable.		
17	Touch Panel Linearity	Less than 2.5% is acceptable.	1.5	
18	LCD Ripple	Touch the touch panel, can not see the LCD ripple. Pen: R 1.0mm silicon rubber. Operation Force: 80g		
19	General appearance	 19.1 Pin type must match type in specification sheet. 19.2 LCD pin loose or missing pins. 19.3 Product packaging must the same as specified on packaging specification sheet. 19.4 Product dimension and structure must conform to product specification sheet. 19.5 product packaging shall be by trays sized to protect tft and fpc cable, 19.6 cable shall not be bent during transportation. 19.7top tray must be empty. 		

11. Handling Precaution

11.1 Handling of LCM

- Avoid external shock.
- Don't apply excessive force on the surface.
- Liquid in LCD is hazardous substance, do not lick or swallow. When the liquid is attaching to your hand, skin, cloth, etc., wash it thoroughly and immediately.
- Don't operate it above the absolute maximum rating.
- Don't disassemble the LCM.
- The operators should wear protections whenever he/she comes into contact with the module. Never touch any of the conductive parts such as the LSI pads, the copper leads on the PCB and the interface terminals with any parts of the human body.
- The modules should be kept in antistatic bags or other containers resistant to static for storage.
- The module is coated with a film to protect the display surface, be careful when peeling off this protective film since static electricity may be generated.

11.2 Storage

- Store it in an ambient temperature of 25±10°C, and in a relative humidity of 50±10%RH. Don't expose to sunlight or fluorescent light.
- Store it in a clean environment, free from dust, active gas, and solvent.
- Store it in anti-static electricity container.
- Store it without any physical load.

11.3 Soldering

- Use only soldering irons with proper grounding and no leakage.
- Iron: no higher than 280±10°C and less than 3 sec during hand soldering.

• Rewiring: no more than 2 times.

12.Packing Method

No.	Item	Dimensions(mm)	Quantity	Remark
1	LCM Module	164.8*99.8*5.6	80PCS	
2	PALLET	370*320*212 (include 80pcs products/one pallet)	1PCS	
3	CARTON	405*355*250 (include 80pcs products/one carton)	1PCS	